

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Inventor Application of: Basceri et al.

Art Unit: 2812

Application No. 09/965,509

Filed: September 26, 2001

For: METHODS FOR FORMING AND
INTEGRATED CIRCUIT STRUCTURES
CONTAINING ENHANCED-SURFACE-AREA
CONDUCTIVE LAYERS

Examiner: Toniae M. Thomas

Date: March 3, 2003

COMMISSIONER FOR PATENTS
WASHINGTON, D.C. 20231

CERTIFICATE OF MAILING

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Attorney for Applicant

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AMENDMENT

In response to the Office action of December 3, 2002, please amend the subject
application as follows:

In the claims:

Please amend claims 30, 31, and 42 as follows:

30. (Amended) An enhanced-surface-area conductive structure in an integrated circuit,
the structure comprising:
a supporting structure;
a conductive layer situated on a surface of the supporting structure; and
a layer of ruthenium oxide having at least one pitted surface situated on the conductive
layer.

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02 FC:1202

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